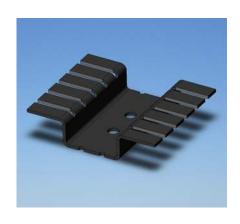
T0-220

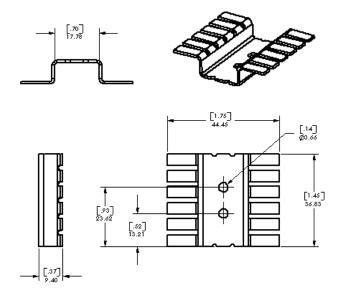
Board Level Heat Sinks



THEITI

P/N: 824302B00000





PRODUCT SPECIFICATIONS

· Devices: TO-220

• Size: 36.8 x 44.5 x 9.4 mm

· Material: Aluminum, 1.0 mm Thick

Weight: 5.0 gramsType: Stamped

PCB Mounting: Device Leads

· Finish: Black Anodized

· Package: Bulk

· Accessories: Hardware & Thermal Interface

Material

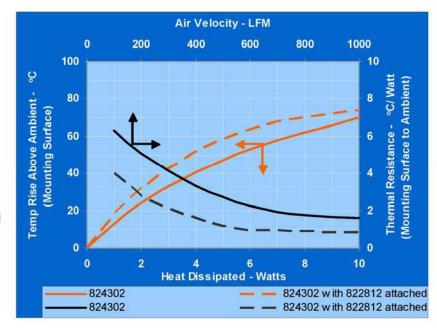
FEATURES & BENEFITS -

- Multiple Holes for Device Attachment
- Dual Device Cooling System
- Mates with PN 822812B00000 For Additional Cooling
- · RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Plating
- · Specialized Body Configurations
- · Contact Applications Engineering



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